

## 64-Pin Super I/O with LPC Interface

### PRODUCT FEATURES

Data Brief

- 3.3 Volt Operation (5V tolerant)
- Programmable Wakeup Event Interface (IO\_PME# Pin)
- SMI Support (IO\_SMI# Pin)
- GPIOs (14)
- Two IRQ Input Pins
- XNOR Chain
- PC2001
- ACPI 2.0 Compliant
- 64-pin TQFP Package
- Intelligent Auto Power Management
- Serial Port
  - One Full Function Serial Port
  - High Speed 16C550A Compatible UART with Send/Receive 16-Byte FIFO
  - Supports 230k and 460k Baud
  - Programmable Baud Rate Generator
  - Modem Control Circuitry
  - Multiple Base I/O Address options and 15 IRQ Options
- Multi-Mode Parallel Port with ChiProtect™
  - Standard Mode IBM PC/XT®, PC/AT®, and PS/2™ Compatible Bidirectional Parallel Port
  - Enhanced Parallel Port (EPP) Compatible - EPP 1.7 and EPP 1.9 (IEEE 1284 Compliant)
  - IEEE 1284 Compliant Enhanced Capabilities Port (ECP)
  - ChiProtect Circuitry for Protection Against Damage Due to Printer Power-On
  - 192 Base I/O Address, 15 IRQ and 3 DMA Options
- LPC Bus Host Interface
  - Multiplexed Command, Address and Data Bus
  - 8-Bit I/O Transfers
  - 8-Bit DMA Transfers
  - 16-Bit Address Qualification
  - Serial IRQ Interface Compatible with Serialized IRQ Support for PCI Systems
  - PCI CLKRUN# Support
  - Power Management Event (IO\_PME#) Interface Pin

**ORDER NUMBER(S):****LPC47N217N-JV FOR 64 PIN, TQFP LEAD-FREE ROHS COMPLIANT PACKAGE**

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## General Description

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The SMSC LPC47N217N is a 3.3V PC 99, PC2001, and ACPI 2.0 compliant Super I/O Controller. The LPC47N217N implements the LPC interface, a pin reduced ISA interface which provides the same or better performance as the ISA/X-bus with a substantial savings in pins used. The part also includes 14 GPIO pins.

The LPC47N217N incorporates a 16C550A compatible UART and one Multi-Mode parallel port with ChiProtect™ circuitry plus EPP and ECP support. The LPC47N217N is easy to use and offers lower system cost and reduced board area.

The LPC47N217N offers a full 16-bit internally decoded address bus, a Serial IRQ interface with PCI CLKRUN# support, relocatable configuration ports, and three DMA channel options.

The parallel port is compatible with IBM PC/AT architectures, as well as IEEE 1284 EPP and ECP. The parallel port ChiProtect™ circuitry prevents damage caused by an attached powered printer when the LPC47N217N is not powered.

The LPC47N217N features Software Configurable Logic (SCL) for ease of use. SCL allows programmable system configuration of key functions such as the parallel port and UART.

The LPC47N217N supports the ISA Plug-and-Play Standard register set (Version 1.0a) and provides the recommended functionality to support Windows operating systems, PC99, and PC2001. The I/O Address, DMA Channel, and Hardware IRQ of each device in the LPC47N217N may be reprogrammed through the internal configuration registers. There are multiple I/O address location options, a Serialized IRQ interface, and three DMA channels.

# Block Diagram

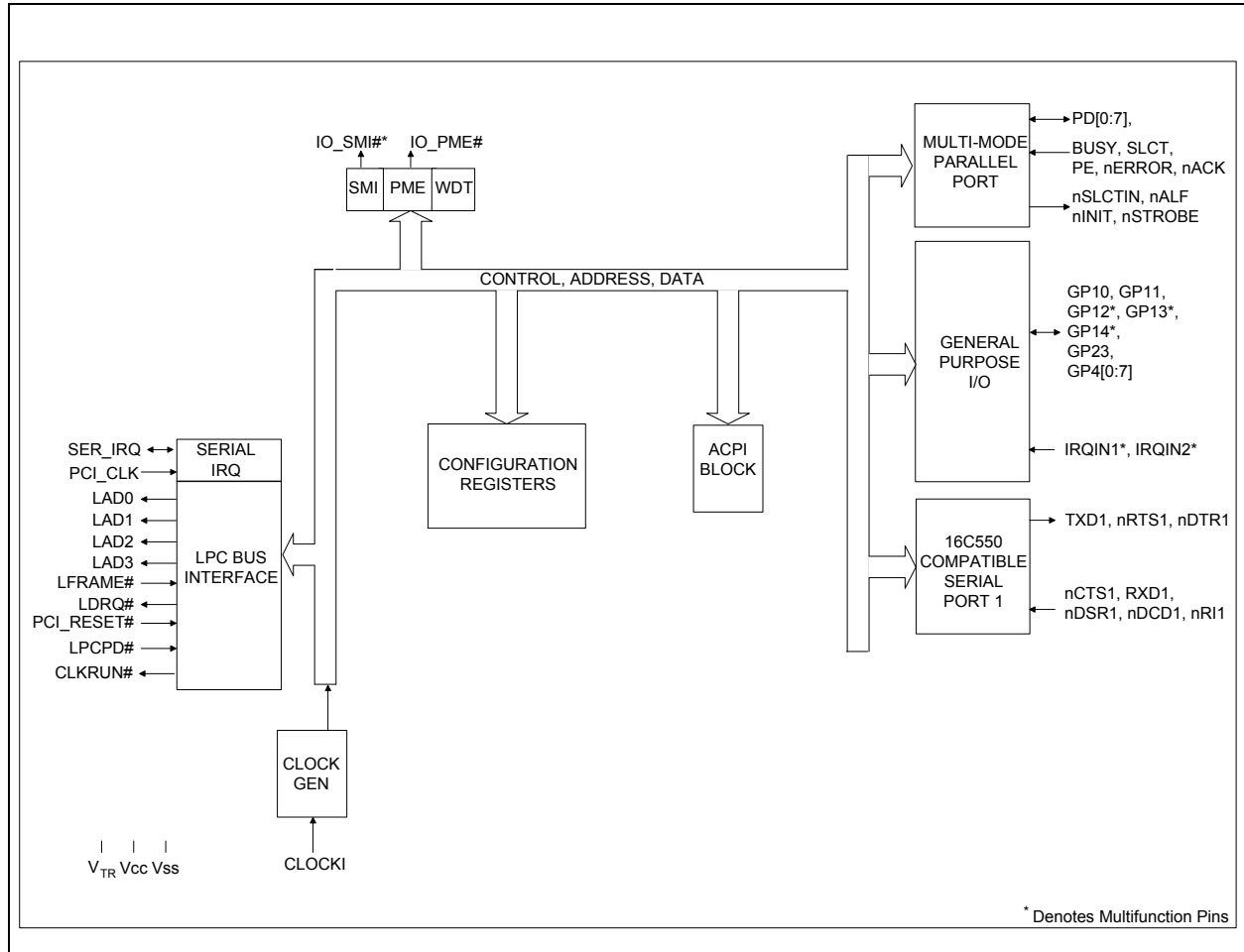


Figure 1 LPC47N217N Block Diagram

## Package Outline

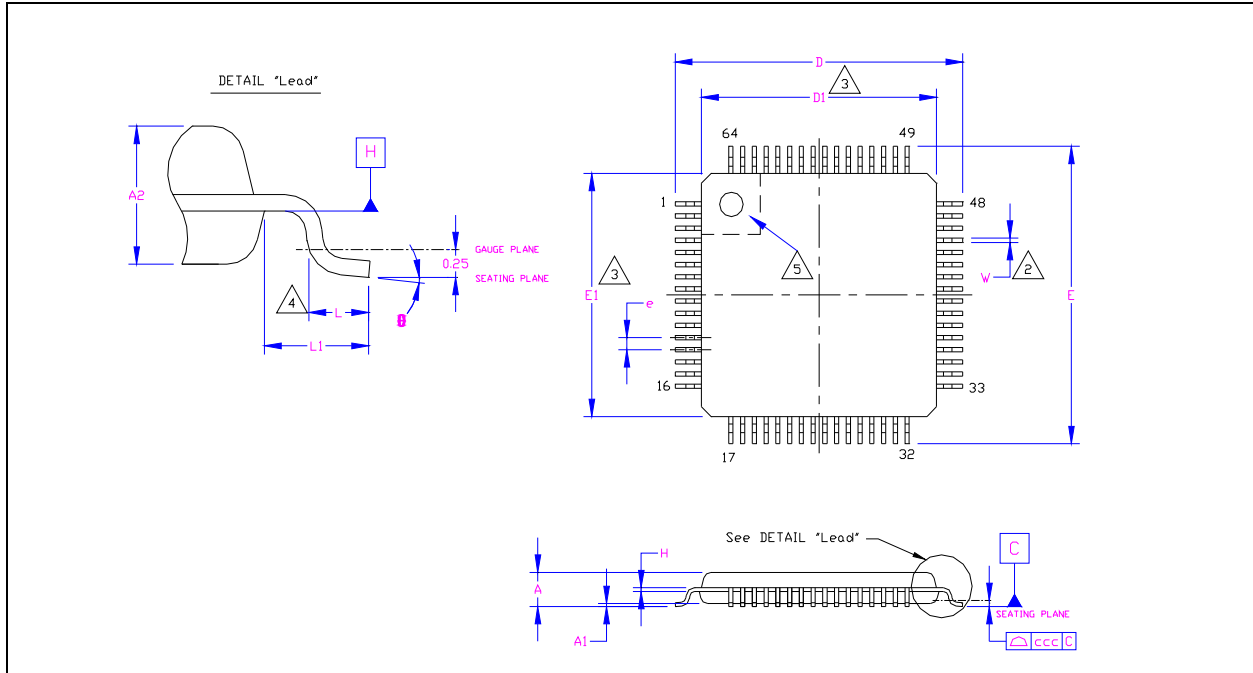


Figure 2 64 Pin TQFP Package Outline, 7X7X1.4 Body, 2 MM Footprint

Table 1 64 Pin TQFP Package Parameters

	MIN	NOMINAL	MAX	REMARKS
A	~	~	1.60	Overall Package Height
A1	0.05	~	0.15	Standoff
A2	1.35	1.40	1.45	Body Thickness
D	8.80	9.00	9.20	X Span
D1	6.80	7.00	7.20	X body Size
E	8.80	9.00	9.20	Y Span
E1	6.80	7.00	7.20	Y body Size
H	0.09	~	0.20	Lead Frame Thickness
L	0.45	0.60	0.75	Lead Foot Length
L1	~	1.00 REF.	~	Lead Length
e	0.40 Basic			Lead Pitch
	0°	~	7°	Lead Foot Angle
W	0.13	0.18	0.23	Lead Width
ccc	~	~	0.08	Coplanarity

**Notes:**

- Controlling Unit: millimeter.
- Tolerance on the true position of the leads is  $\pm 0.035$  mm maximum.
- Package body dimensions D1 and E1 do not include the mold protrusion. Maximum mold protrusion is 0.25 mm per side. D1 and E1 dimensions determined at datum plane H.
- 4 Dimension for foot length L measured at the gauge plane 0.25 mm above the seating plane.
- 5 Details of pin 1 identifier are optional but must be located within the zone indicated.